

## Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

Form Type\*  
Distribute

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information**

### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	<b>Response Date*</b> Sat, Aug 09, 2014 04:04 AM
<b>Contact Name *</b> David Lancaster	Title - Contact Product Ecology	<b>Phone - Contact *</b> 801-562-7455	<b>Email - Contact *</b> david.lancaster@fairchildsemi.com
<b>Authorized Representative *</b> David Lancaster	Title - Representative Product Ecology	<b>Phone - Representative *</b> 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
RGP10B	RGP10B	DO-41 (Plastic)			SUBCONTRACTOR	0.336517	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	Other	Not Applicable	C	seconds	Not Applicable

\* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
<b>RoHS Directive 2011/65/EU</b>	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
<b>RoHS Declaration *</b>	<b>4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions</b>	<b>Supplier Acceptance * Accepted</b>
<p><b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</p>		
Exemption List Version EL-2011/534/EU		
7(a)-Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).		

**Declaration Signature**

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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**Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name DO-41 (Plastic)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.880	Supplier		Silicon	0.880	7440-21-3	2615
Encapsulation	Thermoplastics	123.570	B	Antimony/Antimony Compounds	Antimony Trioxide	2.750	1309-64-4	8172
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	2.750	6386-73-8	8172
			Supplier		Carbon Black	1.370	1333-86-4	4071
			Supplier		Epoxy Resin	20.600	29690-82-2	61215
			Supplier		Silica, vitreous	96.100	60676-86-0	285573
Lead Wire	Other Ferrous alloys, non-stainless steels	201.201	Supplier		Copper	201.000	7440-50-8	597296
			Supplier		Iron	0.161	7439-89-6	478
			Supplier		Phosphorus	0.040	7723-14-0	119
Marking Ink	Other Organic Materials	0.200	Supplier		2-Propenoic acid polymer	0.130	53192-18-0	386
			Supplier		Aluminum	0.030	7429-90-5	89
			Supplier		Padimate	0.020	21245-01-2	59
			Supplier		Silica	0.010	112945-52-5	30
			Supplier		additive	0.010	947-19-3	30
Plating	Other Nonferrous metals & alloys	4.300	Supplier		Tin	4.300	7440-31-5	12778
Silicon Rubber	Other inorganic materials	5.100	Supplier		Silicon	5.100	7440-21-3	15155
Solder Wafer	Other Nonferrous metals & alloys	1.265	A	Lead/Lead Compounds	Lead	1.170	7439-92-1	3477
			Supplier		Silver	0.032	7440-22-4	94
			Supplier		Tin	0.064	7440-31-5	189